

PB No	Paper ID	Title/Author(s)
1	147	<b>Power Estimation and Comparison of Heterogeneous CPU-GPU Processors</b> Kaur, Rupinder; Mohammadi, Farah <i>Toronto Metropolitan University, Canada</i>
2	173	<b>Stretchability of Electronic Components Assembled on Fabric for Wearable Electronics Applications</b> Salam, Budiman; Tan, Rachel Lee Siew <i>Singapore Institute of Manufacturing Technology, Singapore</i>
3	179	<b>Chemical Deburring as Process Solution for Eliminating Sn Metal Burrs of Wettable Flank QFN Devices</b> Serapio, Rohn Kenneth Listangco; Antilano, Ernesto Jr. Tarosan; Gablan, Alyssa Grace Sarmiento; Soreda, Alvin Salloman; <i>STMicroelectronics, Inc., Philippines</i>
4	184	<b>Paddle Tilt Towards Mold Flash Performance on Small Diode Package</b> Kow, Siew Ting; Ooi, Choo Tian; Ting, Jia Uunn; Khairul Ikhsan, Yahaya <i>Nexperia msia sdn bhd, Malaysia</i>
5	187	<b>Wirebond Stability Resolution on Automotive MEMS Device Through Tape Adhesion Thickness and Plasma Characterization</b> Bamba, Behra Esposito; Gomez, Frederick Ray Insular; Rillera, Jane Wanzel Estrellado <i>STMicroelectronics, Inc., Philippines</i>
6	238	<b>Physical Verification for 3D Heterogeneous Integrated Electronic Photonic Integration designs using Calibre eqDRC for Non-Manhattan structures</b> Mani, Raju (1); Nair Gourikutty, Sajay Bhuvanendran (1); Dutta, Rahul (1); Liow, Jason (2) <i>1: ASTAR Institute of Microelectronics, Singapore; 2: Raintree Photonics, Singapore</i>
7	242	<b>Mold Bleed Effacing On Leaded Package With Intentional Coining Concept In Transfer Molding Process Applications</b> Hazizan, Asyraq; Koo, Chee Aung; Jamal, Fakhrul Izzat <i>Nexperia Malaysia Sdn. Bhd, Malaysia</i>
8	299	<b>Patterning on reflective (Al) surface using auto alignment in immersion lithography to achieve tight overlay for reconfigurable metasurface devices</b> Sundaram, Arvind; Pitchappa, Prakash; Guz, Zhonghua; Yoo, Jae Ok; Singh, Navab <i>Institute of Microelectronics, Singapore</i>
9	315	<b>A novel packaging solution for 400G photonic engine</b> Xu, Feng; Li, Zhenyu; Lee, Wen <i>A*STAR, Singapore</i>
10	344	<b>Warpage Behaviour of Different Fan-out Chip First Wafers</b> Sanchez, Debbie-Claire <i>ERS electronic GmbH, Germany</i>
11	349	<b>Effect of Tg and modulus on the underfill reliability in package</b> Zhao, Guolin (1,2); Lin, Haoliang (2); Peng, Xiaohui (2); Zhu, Pengli (2); Zhu, Wenhui (1) <i>1: Central South University, China; 2: Shenzhen Institute of Advanced Electronic Materials, Shenzhen Institute of Advanced Technology, Chinese Academy of Sciences</i>
12	361	<b>The Study of Process Enhancements to Improve Flash Removal Performance for Power Packages</b> Lee, Wai Wai; Abd Hamid, Hazrul Alang; Ting, Jia Yunn <i>Nexperia Malaysia Sdn. Bhd, Malaysia</i>
13	375	<b>Overcoming Assembly Process Challenges in Glass Interposer: Development of Jigs and Fixtures</b> Ubed, Mohammed; Pamidighantam, Ramana; Veerandi, Anusha; Yeluripati, Rohin Kumar <i>LightSpeed Photonics Private Limited., Singapore</i>
14	383	<b>Analysis on bonding wires of Au-Coated Ag alloy for IBGA automotive application</b> Palagud, Jose (1); Lim, Teck Siang (1); Solehah, Jasmee (1,2); Nur Dianalzzani, Masdzarif (1,2); Hoo, Kok Inn (1); Wang, Soon Wei (1); Ghazali, Omar (2) <i>1: On Semi, Malaysia; 2: Universiti Teknikal Malaysia Melaka , UTeM</i>